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SEMICONDUCTOR



ESD



TVS



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PLED

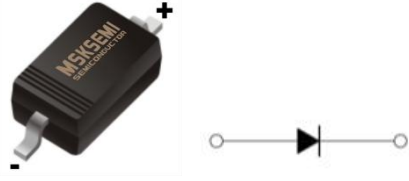

MMSD914

Product specification

FEATURES

- High Voltage

Reference News

| PACKAGE OUTLINE | MARKING |
|---|---|
|  <p>SOD-123</p> |  |

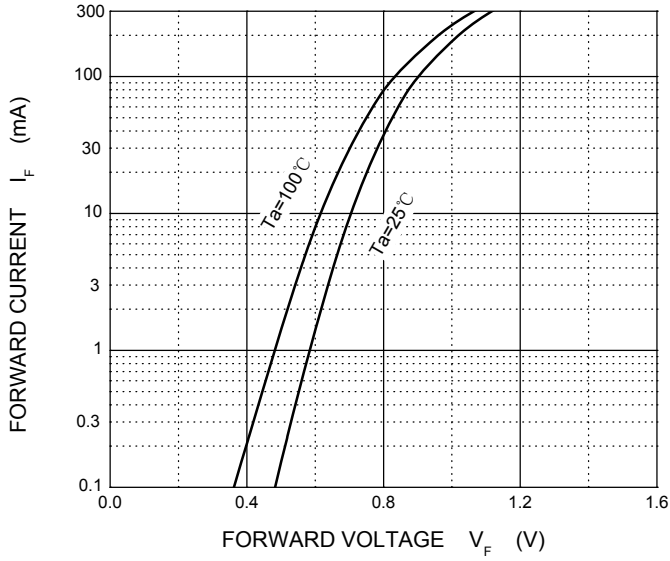
MAXIMUM RATINGS (Ta=25°C unless otherwise noted)

| Symbol | Parameter | Value | Unit |
|-----------------|---|----------|------|
| V_{RRM} | Maximum Repetitive Reverse Voltage | 100 | V |
| I_o | Forward Current | 0.2 | A |
| I_{FSM} | Non-repetitive Peak Forward Surge Current @t= 8.3ms | 2 | |
| P_D | Power Dissipation | 400 | mW |
| $R_{\theta JA}$ | Thermal Resistance from Junction to Ambient | 312 | °C/W |
| T_j, T_{stg} | Operation Junction and Storage Temperature Range | -55~+150 | °C |

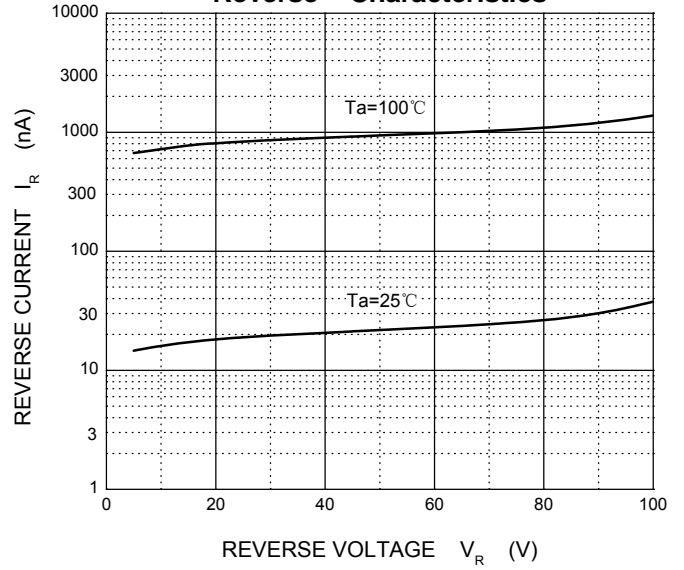
ELECTRICAL CHARACTERISTICS(Ta=25°C unless otherwise specified)

| Parameter | Symbol | Test conditions | Min | Typ | Max | Unit |
|-----------------------|------------|---|-----|-----|-----|---------|
| Reverse voltage | $V_{(BR)}$ | $I_R=100\mu A$ | 100 | | | V |
| Reverse current | I_R | $V_R=20V$ | | | 25 | nA |
| | | $V_R=75V$ | | | 5 | μA |
| Forward voltage | V_F | $I_F=10mA$ | | | 1 | V |
| Total capacitance | C_{tot} | $V_R=0V, f=1MHz$ | | | 4 | pF |
| Reverse recovery time | t_{rr} | $I_F= I_R=10mA, I_{rr}=0.1 \times I_R, R_L=100\Omega$ | | | 4 | ns |

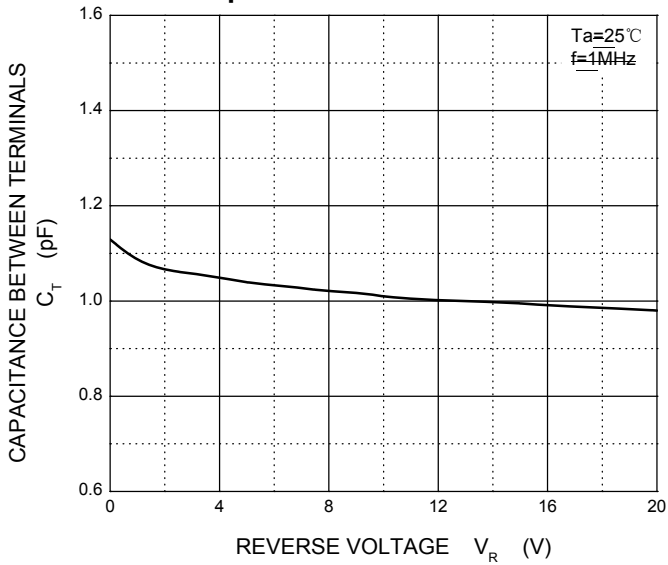
Forward Characteristics



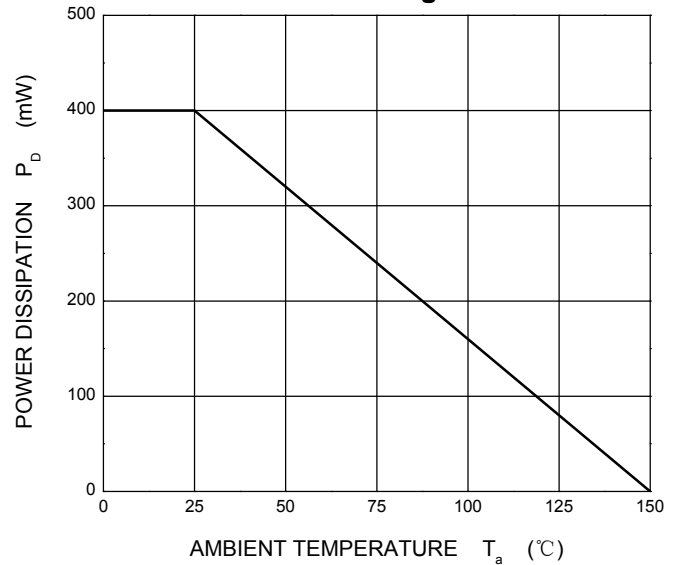
Reverse Characteristics



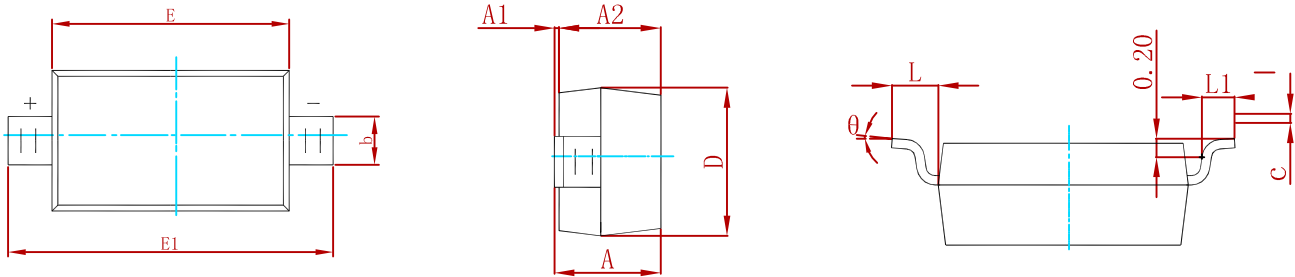
Capacitance Characteristics



Power Derating Curve

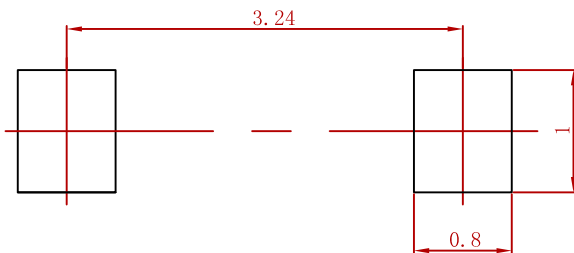


PACKAGE MECHANICAL DATA



| Symbol | Dimensions In Millimeters | | Dimensions In Inches | |
|--------|---------------------------|-------|----------------------|-------|
| | Min | Max | Min | Max |
| A | 1.050 | 1.250 | 0.041 | 0.049 |
| A1 | 0.000 | 0.100 | 0.000 | 0.004 |
| A2 | 1.050 | 1.150 | 0.041 | 0.045 |
| b | 0.450 | 0.650 | 0.018 | 0.026 |
| c | 0.080 | 0.150 | 0.003 | 0.006 |
| D | 1.500 | 1.700 | 0.059 | 0.067 |
| E | 2.600 | 2.800 | 0.102 | 0.110 |
| E1 | 3.550 | 3.850 | 0.140 | 0.152 |
| L | 0.500 REF | | 0.020 REF | |
| L1 | 0.250 | 0.450 | 0.010 | 0.018 |
| θ | 0° | 8° | 0° | 8° |

Suggested Pad Layout



- Note:
1. Controlling dimension: in millimeters.
 2. General tolerance: ± 0.05 mm.
 3. The pad layout is for reference purposes only.

REEL SPECIFICATION

| P/N | PKG | QTY |
|---------|---------|------|
| MMSD914 | SOD-123 | 3000 |

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